

SPECIFICATIONS

Mechanical

Contact Retention Force: 0.30Kg (0.66Lbs) min. per contact

Durability: 25 Cycles

Insertion Force(Conn. Into PCB): 6.8Kg (15Lbs)

Unmating Force(Per Contact pair): 14g min.

Electrical

Current Rating: 0.75 Amps max.

Insulation Resistance: 1M Ω min. at 500V DC

Dielectric Withstanding Voltage: 500V DC at Sea Level

Low Level Contact Resistance: 10m Ω max. initial, No change greater than 10 milliohms max after full environmental testing.

Physical

Housing: High temperature thermoplastic, UL 94V-0 rated in Black Color

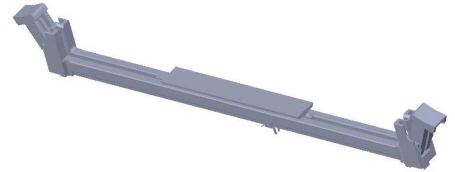
Contact: Copper alloy

Ejector: Thermoplastic, UL 94V-0 rated in Black Color

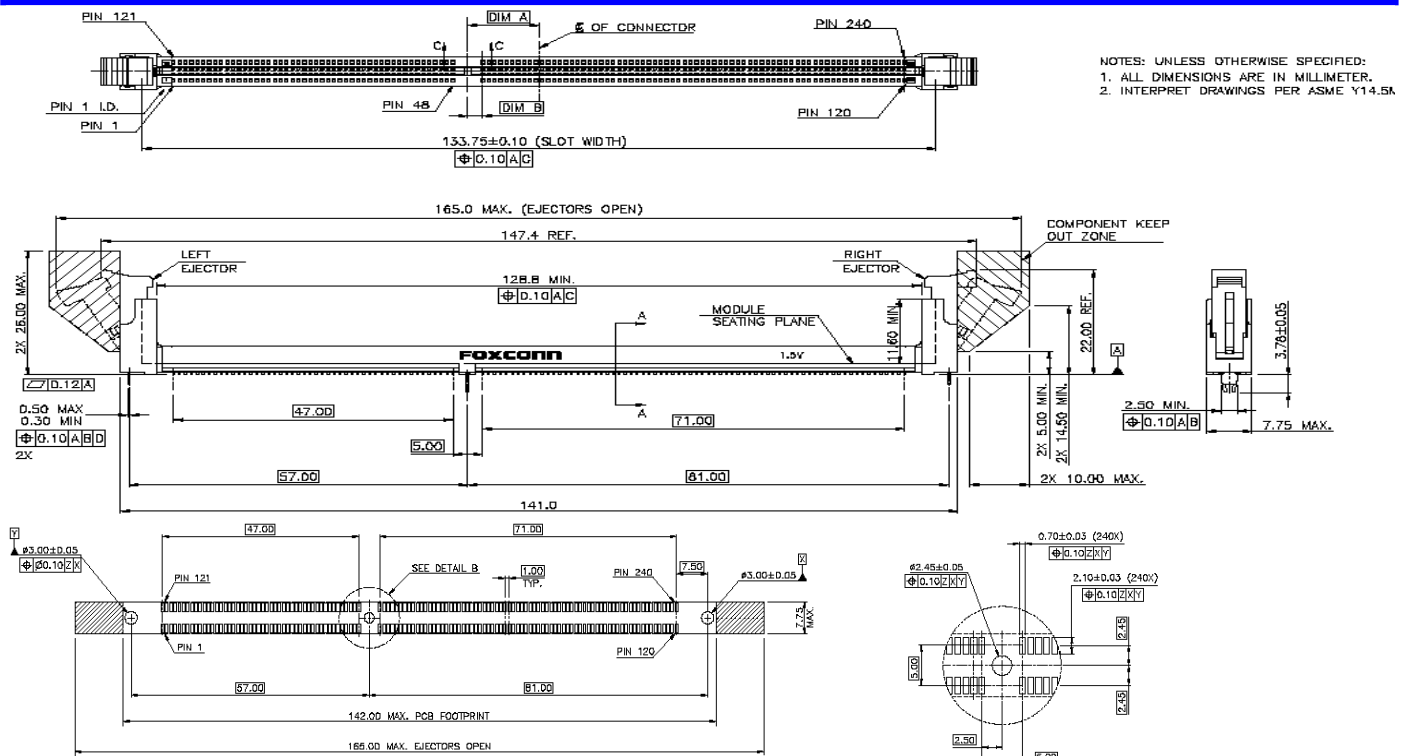
Metal Hold Down: Copper alloy

Operating Temperature: 0°C to +85°C

ATS40 Series
VLP SMT DDR3
1.00mm Pitch
240 Pos.



DRAWING



ORDERING INFORMATION

PRODUCT NOMENCLATURE:

PRODUCT NO. : A TS 40 * - T C * C - 3 *

MEMORY SOCKET

DDR III DIMM
VERTICAL 1.00 MM PITCH,
SMT TYPE

QTY OF CONTACTS:
40 = 240 POSITION

PLATING TYPE
F = LEAD FREE
M = MATTE TIN

TRAY TYPE
3 = HARD TRAY + COVER

EXTENSION CODE
TCBC = WHITE EJECTOR
TCDC = BLACK EJECTOR

CONTACT AREA GOLD PLATING
1 = GOLD FLASH
3 = 30 u" Min. Au
7 = 15 u" Min. Au

PCB THICKNESS
8 = SMT TYPE FOR 2.36 THICKNESS PCB
9 = SMT TYPE FOR 1.57 THICKNESS PCB

PART NUMBER	POSITION	MARKING	POSITION	DIM. A	DIM. B	DIM. C	PCB THICKNESS
ATS409*-TC*C-3*	240	1.5V	CENTER OFFSET	12.00	2.50	1.90	1.57±0.13
ATS408*-TC*C-3*	240	1.5V	CENTER OFFSET	12.00	2.50	2.60	2.36±0.13